

Device Specification

ELECTRICAL CHARACTERISTICS



| Part Number | I_{hold} (A) | I_{trip} (A) | V_{max} (Vdc) | I_{max} (A) | P_d typ (W) | Maximum Time To Trip | | Resistance | |
|-------------|-------------------|-------------------|--------------------|------------------|------------------|----------------------|----------------|---------------------------|----------------------------|
| | | | | | | Current (A) | Time (Sec.) | R_{min} (Ω) | R_{1max} (Ω) |
| SPR-P260T | 2.60 | 5.20 | 6 | 50 | 0.6 | 8.0 | 4.0 | 0.010 | 0.035 |

Note: I_{hold} = Hold current: maximum current device will pass without tripping in 23 °C still air.

I_{trip} = Trip current: minimum current at which the device will trip in 23 °C still air.

V_{max} = Maximum voltage device can withstand without damage at rated current (I_{max})

I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max})

P_d = Power dissipated from device when in the tripped state at 23 °C still air.

R_{min} = Minimum resistance of device in initial (un-soldered) state.

R_{1max} = Maximum resistance of device at 23 °C measured one hour after tripping or reflow soldering of 260 °C for 20 sec.

*Value specified were determined using the PWB with 0.030" * 1.5oz copper traces.

*Customer should verify the device performance in their specified conditions.

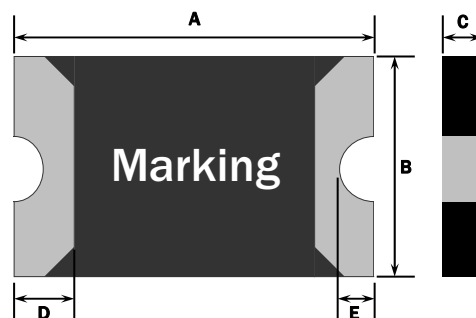
Caution: Operation beyond the specified rating may result in damage and possible arcing and flame.

Recognitions:   

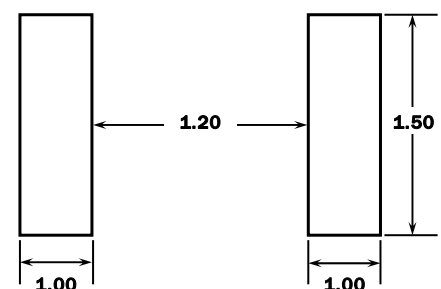
Marking

Polytronics / Polystar Logo
 P_U
 Part Identification

Figure



Recommended Pad Layout (mm)



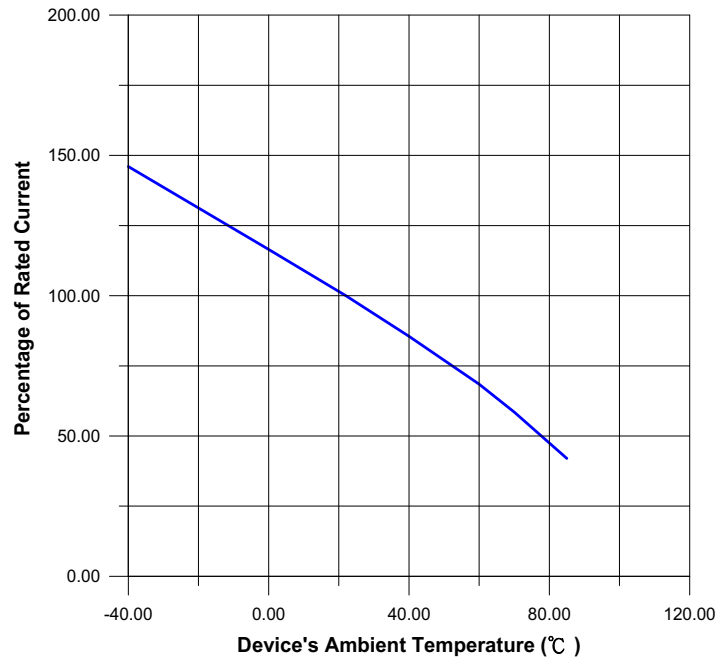
Note: Polystar is Polytronics's manufacturing site in China. The Polystar ID marking shall appear on smallest package.

PHYSICAL DIMENSIONS (mm)

| Part Number | A | | B | | C | | D | | E | |
|-------------|------|------|------|------|------|------|------|------|------|------|
| | Min. | Max. | Min. | Max. | Min. | Max. | Min. | Max. | Min. | Max. |
| SPR-P260T | 2.00 | 2.20 | 1.20 | 1.50 | 0.40 | 0.75 | 0.20 | 0.55 | 0.05 | 0.45 |

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Thermal Derating Curve

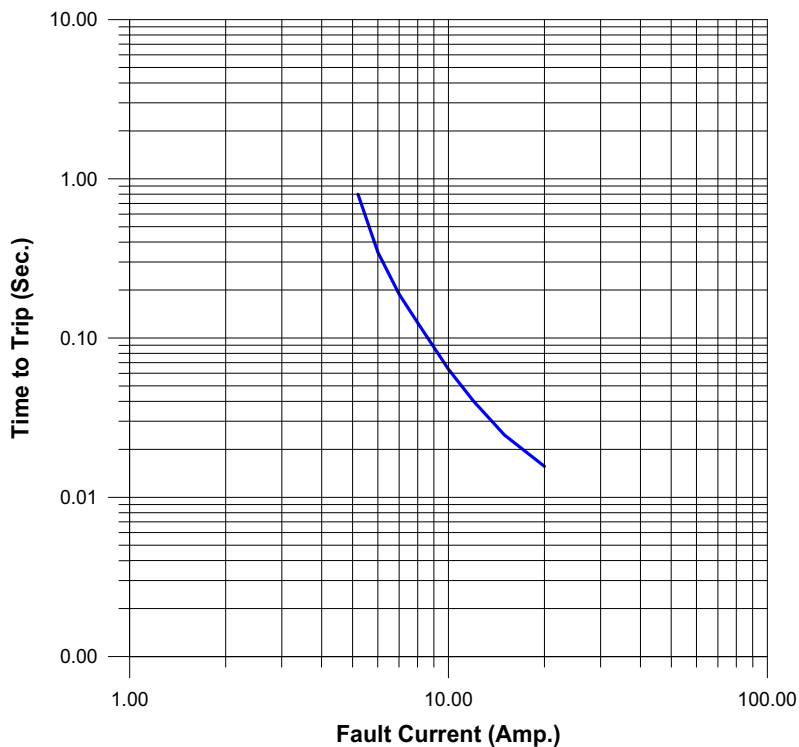


Thermal Derating Chart

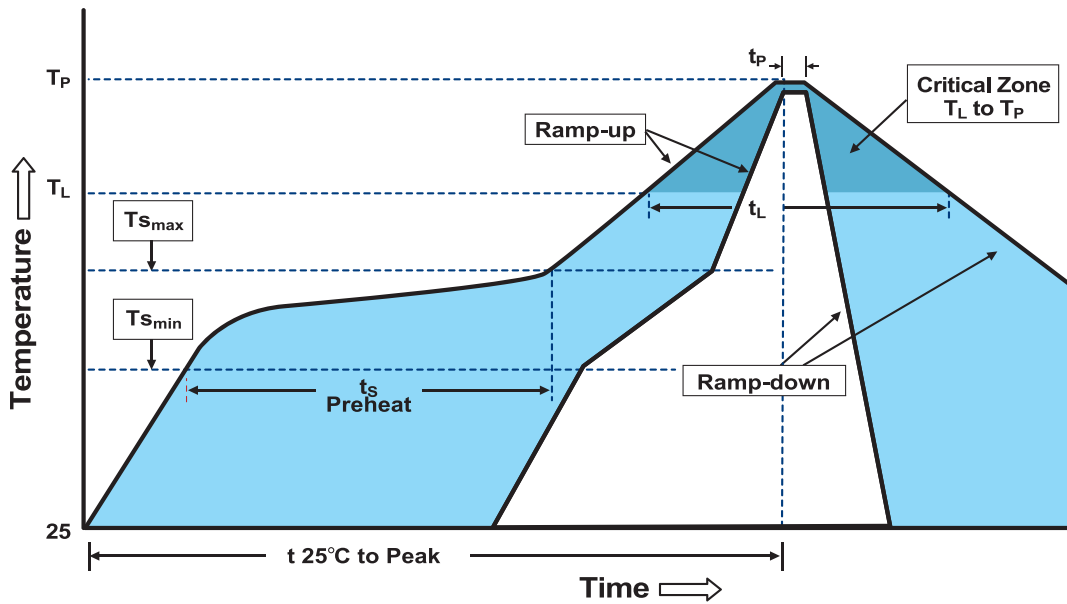
Recommended Hold Current (A) at Ambient Temperature (°C)

| Part Number | Ambient Operation Temperature | | | | | | | | |
|-------------|-------------------------------|--------|------|-------|-------|-------|-------|-------|-------|
| | -40 °C | -20 °C | 0 °C | 23 °C | 40 °C | 50 °C | 60 °C | 70 °C | 85 °C |
| SPR-P260T | 3.80 | 3.30 | 2.90 | 2.60 | 2.20 | 1.95 | 1.75 | 1.50 | 1.05 |

Average Time-Current Curve



Soldering Parameters



| Profile Feature | Pb-Free Assembly |
|--|--------------------|
| Average Ramp-Up Rate (T_{smax} to T_P) | 3°C/second max. |
| Preheat | |
| -Temperature Min (T_{smin}) | 150°C |
| -Temperature Max (T_{smax}) | 200°C |
| -Time (T_{smin} to T_{smax}) | 60-180 seconds |
| Time maintained above: | |
| -Temperature (T_L) | 217°C |
| -Time (t_L) | 60-150 seconds |
| Peak Temperature (T_P) | 260°C |
| Time within 5°C of actual Peak Temperature (t_P) | 20-40 seconds |
| Ramp-Down Rate | 6 °C /second max. |
| Time 25°C to Peak Temperature | 8 minutes max. |
| Storage Condition | 0°C ~35°C, ≤ 70%RH |

- Recommended reflow methods: IR, vapor phase oven, hot air oven, N₂ environment for lead-free
- Recommended maximum paste thickness is 0.25mm (0.010 inch)
- Devices can be cleaned using standard industry methods and solvents.

Note 1: All temperature refer to topside of the package, measured on the package body surface.

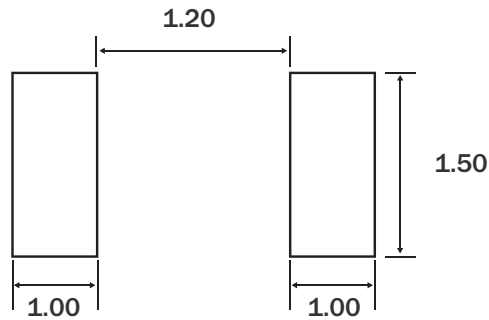
Note 2: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Environmental Specifications

| | |
|---|---------------------|
| Operating/Storage Temperature | -40°C to +85 °C |
| Maximum Device Surface Temperature in Tripped State | 125°C |
| Moisture Sensitivity Level | Level 1, J-STD-020C |

Packaging Quantity and Marking

Recommended Pad Layout (mm.)



| Part Number | Marking | Quantity |
|-------------|---------|----------|
| SPR-P260T | U | 4000 |

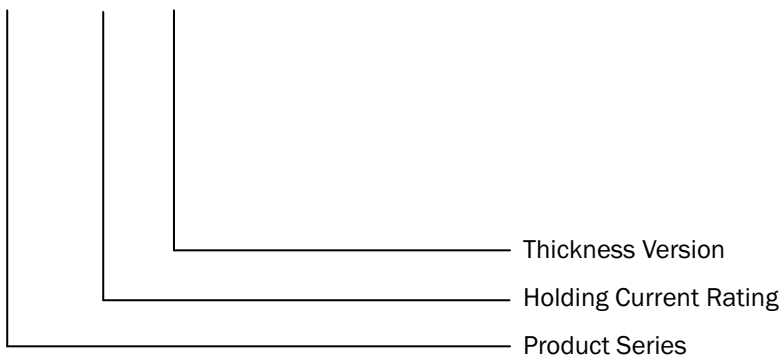
© 8 mm tape on 7 inch reel per EIA-481-1 (equivalent to IEC286, part 3)

Physical Specifications

| | |
|--------------------|--|
| Terminal Material | Solder-Plated Copper (Solder Material: Matte Tin (Sn)) |
| Lead Solderability | Meets EIA Specification RS186-9E, ANSI/J-STD-002 Category 3. |

Part Number System

SPR - P □□□ I



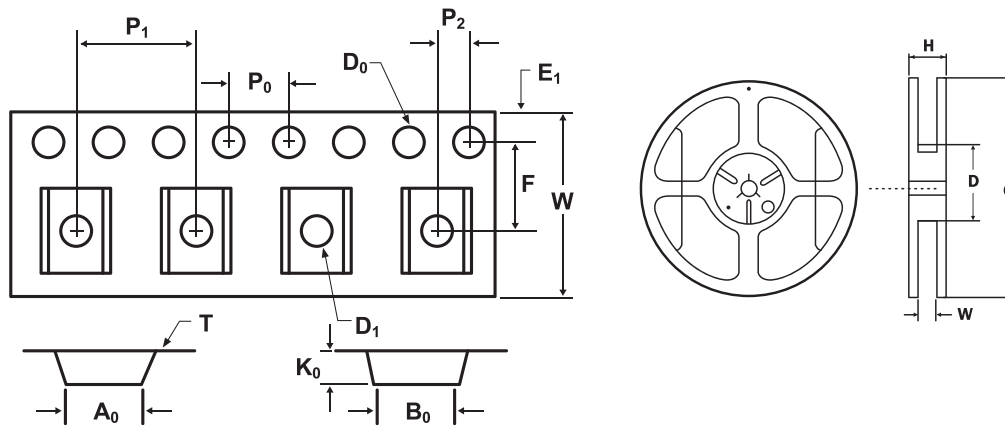
SPR-P = 0805 Surface Mount PTC Devices

Tape Specifications: EIA-481-1 (mm.)

| | |
|----------------|-------------|
| W | 8.00 ± 0.10 |
| F | 3.50 ± 0.05 |
| E ₁ | 1.75 ± 0.10 |
| D ₀ | 1.55 ± 0.05 |
| D ₁ | 1.00 (min) |
| P ₀ | 4.00 ± 0.08 |
| P ₁ | 4.00 ± 0.10 |
| P ₂ | 2.00 ± 0.05 |
| A ₀ | 1.60 ± 0.10 |
| B ₀ | 2.30 ± 0.10 |
| T | 0.25 ± 0.10 |
| K ₀ | 0.90 ± 0.10 |
| Leader min. | 390 |
| Trailer min. | 160 |

Reel Dimensions: EIA-481-1 (mm.)

| | |
|---|-------------|
| C | Ø178 ± 1.0 |
| D | Ø60.2 ± 0.5 |
| H | 11.0 ± 0.5 |
| W | 9.0 ± 1.5 |



单击下面可查看定价，库存，交付和生命周期等信息

[>>聚鼎](#)